# **M2 Series**









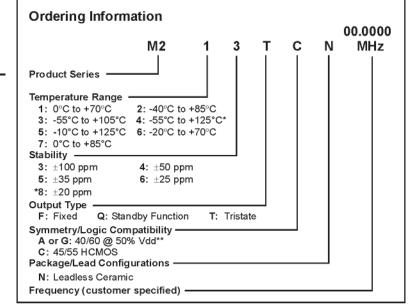


#### Features:

- Leadless Chip Carrier (LCC) package
- Seam sealed package
- Tri-state or Standby function options
- Stabilities to ±20 ppm
- Fully RoHS 6 compliant

## Applications:

- Microprocessors/Controllers, DSP
- Gig E, SONET
- **Industrial Controllers**
- **Broadband Access**
- Test & Measurement Equipment



\*Contact Factory for Availability

\*\* A and G codes are used interchangeably on the M2 Series

M2002Sxxx - Contact factory for datasheet

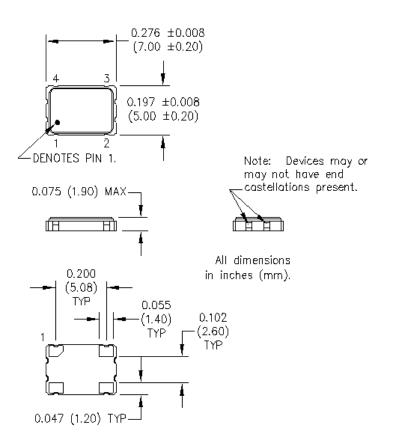
		Symbol	Min.	Typ.	Max.	Units	Condition/Notes	
	Frequency Range	F	1.5		135	MHz	See Note 1	
	Operating Temperature	TA	(See ordering information)					
	Storage Temperature	Ts	-55		+125	°C		
	Frequency Stability	ΔF/F	(See ordering information)					
	Aging							
	1 <sup>st</sup> Year			±3		ppm		
	Thereafter (per year)			±2		ppm		
	Input Voltage	Vdd	3.0	3.3	3.6	٧		
	Input Current	ldd			10	mA	1.500 to 20.000 MHz	
ဖ					20	mA	20.001 to 50.000 MHz	
ا ا					30	mA	50.001 to 67.000	
äŧi					55	mA	67.001 to 135.000 MHz	
Electrical Specifications	Standby Current				10	μΑ	"Q" Output Type Only	
l e	Output Type						HCMOS/TTL Compatible	
Ñ	Load				15/2	PF/TTL	See Note 2	
cal	Symmetry (Duty Cycle)		(See ordering information)			½ Vdd		
냹	Logic "1" Level	Voh	90% Vdd			٧	HCMOS Load	
<u>e</u>			Vdd -0.5			V	TTL Load	
"	Logic "0" Level	Vol			10% Vdd	٧	HCMOS Load	
					0.5	V	TTL Load	
	Output Current				±4	mA		
	Rise/Fall Time	Tr/Tf					See Note 3	
					6	ns	1.500 to 50.000 MHz	
					4	ns	50.001 to 80.000 MHz	
					2	ns	80.001 to 135.000 MHz	
	Standby/Tristate Function		Input Logic "1" or floating: output active					
			Input Logic "0"; output disables to high-Z					
	Start up Time				10	ms		
Ш	Random Jitter	Rj		4	10	ps RMS	1-Sigma	
<del> </del>	Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 mS duration, ½ sinewave)						
ent	Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)						
Ĭ	Hermeticity	Per MIL-STD-202, Method 112, (1x10 <sup>-8</sup> atm. cc/s of Helium)						
2	Thermal Cycle	Per MIL-STD-883, Method 1010, Condition B (-55°C to +125°C, 15 min. dwell, 10 cycles)						
Environmental	Solderability	Per EIAJ-STD-002						
Ш	Soldering Conditions	See solder profile, Figure 1						

- 1. Consult factory for availability of higher frequencies.
- 2. HCMOS Load See Load circuit diagram. Consult factory with nonstandard output load requirements.

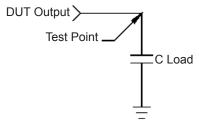
  3. Rise/Fall times are measured between 0.5 V and 2.4 V with TTL load, and between 10% Vdd and 90% Vdd with HCMOS load.

MtronPTI reserves the right to make changes to the product(s) and service(s) described herein without notice. No liability is assumed as a result of their use or application.



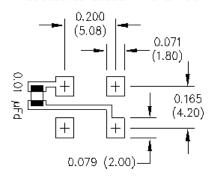


## **Load Circuit Diagram**



Note: C Load includes probe and fixturing.

#### SUGGESTED SOLDER PAD LAYOUT



Pin Connections						
PIN	IN Function					
1	N/C, Tristate or Standby					
2	Ground					
3	Output					
4	+Vdd					





